



Semiconductor Device Type: 004 UDFN 1.2x1.2x0.6 NiPdAu (HEA)			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	(mg) Total	Mold Compound	% of Total Weight	
Silica, fused	60676-86-0	Mold Compound	43.101	1.034	431,010	1.15	60676-86-0	90.00	47.89
Epoxy Resin	Trade Secret	Mold Compound	2.323	0.056	23,227				
Phenolic Resin	Trade Secret	Mold Compound	2.323	0.056	23,227				
Carbon Black	1333-86-4	Mold Compound	0.144	0.003	1,437				
Copper	7440-50-8	Lead Frame	39.377	0.945	393,773				
Iron	7439-89-6	Lead Frame	0.931	0.022	9,308	Total 100.00			
Phosphorous	7723-14-0	Lead Frame	0.101	0.002	1,012	0.97	Lead Frame	% of Total Weight	40.47
Zinc (Metal)	7440-66-6	Lead Frame	0.061	0.001	607				
Copper	7440-50-8	Chip on frame	0.632	0.015	6,322				
Tin	7440-31-5	Chip on frame	0.122	0.003	1,222				
Polymide	Trade Secret	Chip on frame	0.110	0.003	1,101				
Nickel	7440-02-0	Chip on frame	0.025	0.001	250	Total 100.00			
Titanium	7440-32-6	Chip on frame	0.001	0.000	5	0.02	Chip on Frame	% of Total Weight	0.89
Silicon	7440-21-3	Chip (Die)	10.000	0.240	100,000				
Nickel	7440-02-0	Plating on external leads (pins)	0.675	0.016	6,750				
Palladium	7440-05-3	Plating on external leads (pins)	0.038	0.001	375				
Gold	7440-57-5	Plating on external leads (pins)	0.038	0.001	375				
TOTALS:			100.000	2.400	1,000,000				
0.0024 g Total Mass									
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero))									
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and/or analytical test data.									
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.									
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/									
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.									
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table									
						2.40			100.00